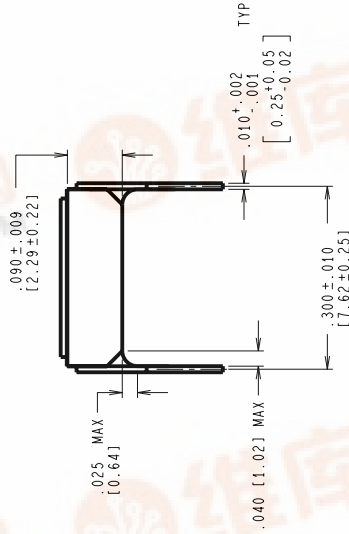
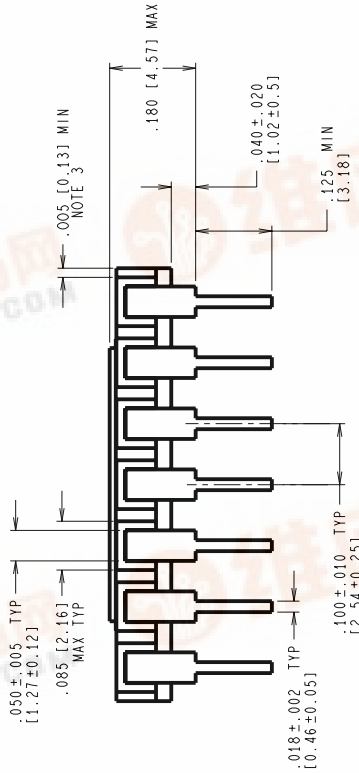
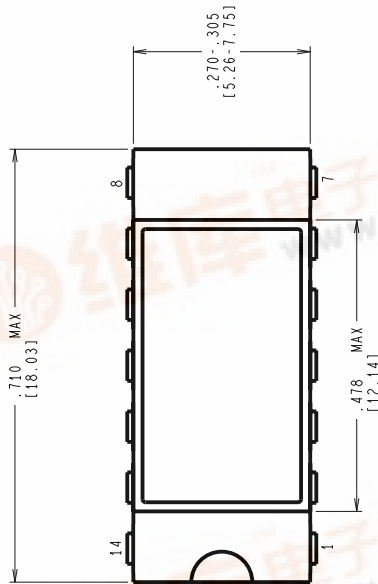


REVISIONS			
LTR	DESCRIPTION	E.C.N.	DATE
H	REVISE AND REDRAW PER NEW STANDARD.	10257	02/08/94
J	.085 MAX WAS .080 ± .008; .270-.305 WAS .290 ± .003.	10474	06/30/94



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED.

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 200 MICROINCHES/5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - 50 MICROINCHES/1.27 MICROMETERS MINIMUM GOLD OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.
- LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.
- DIMENSION .005 IN/0.13mm MINIMUM SHALL BE MEASURED FROM THE EDGE OF THE FURTHEST EXTENSION OF THE METAL PAD OR LEAD.
- REFERENCE JEDEC REGISTRATION MS-015, VARIATION AB, DATED 7/90.

MIL-M-38510
CONFIGURATION CONTROL

MIL/AERO
CONFIGURATION CONTROL

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION			
DRAWN: <i>Deyley Gray</i>	02/08/94	SCALE	SIZE	DRAWING NUMBER	REV
DESIGNED: <i>CHK</i>		N/A	C	MKT-D14D	J
ENGR: <i>CHK</i>		DIP, SIDEBRAZED CERAMIC, 14 LEAD			
APPROVAL		2800 Semiconductor Drive, Santa Clara, CA 95052-8090			
PROJECTION		DO NOT SCALE DRAWING			
INCH		SHEET 1 of 1			